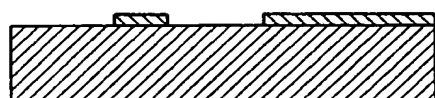
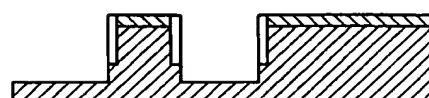




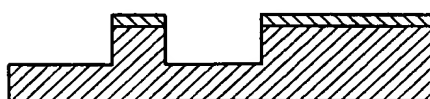
FIG. 1
(Prior Art)



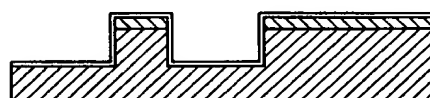
Oxide deposition
and patterning



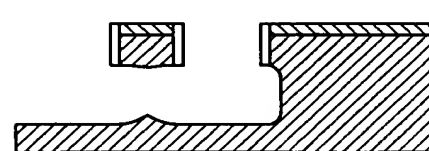
Silicon deep etch



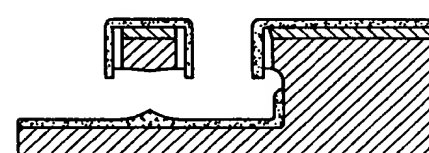
Silicon deep etching



Sidewall passivation



Release etch



Sputter metallization



not
approved
jc 6/13/03



FIG. 2
(Prior Art)

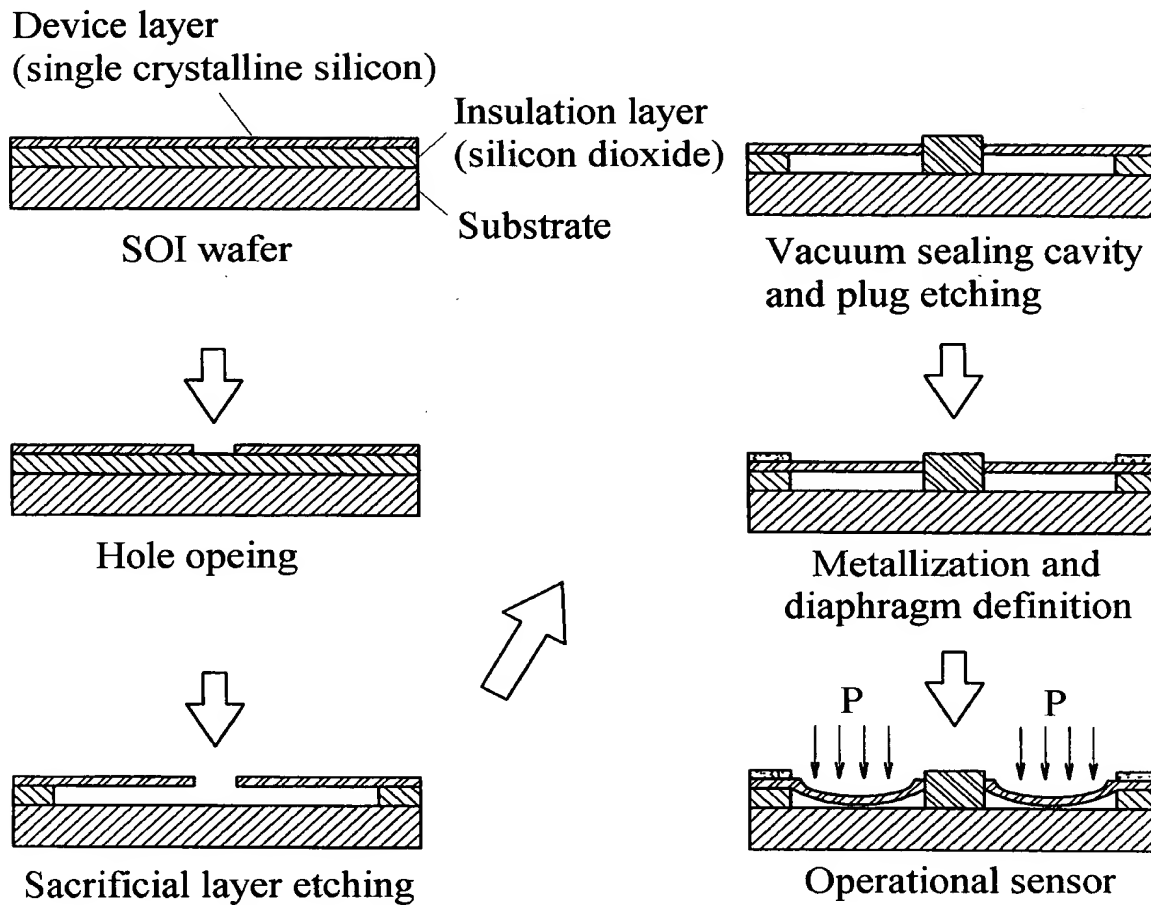




FIG. 3
(Prior Art)

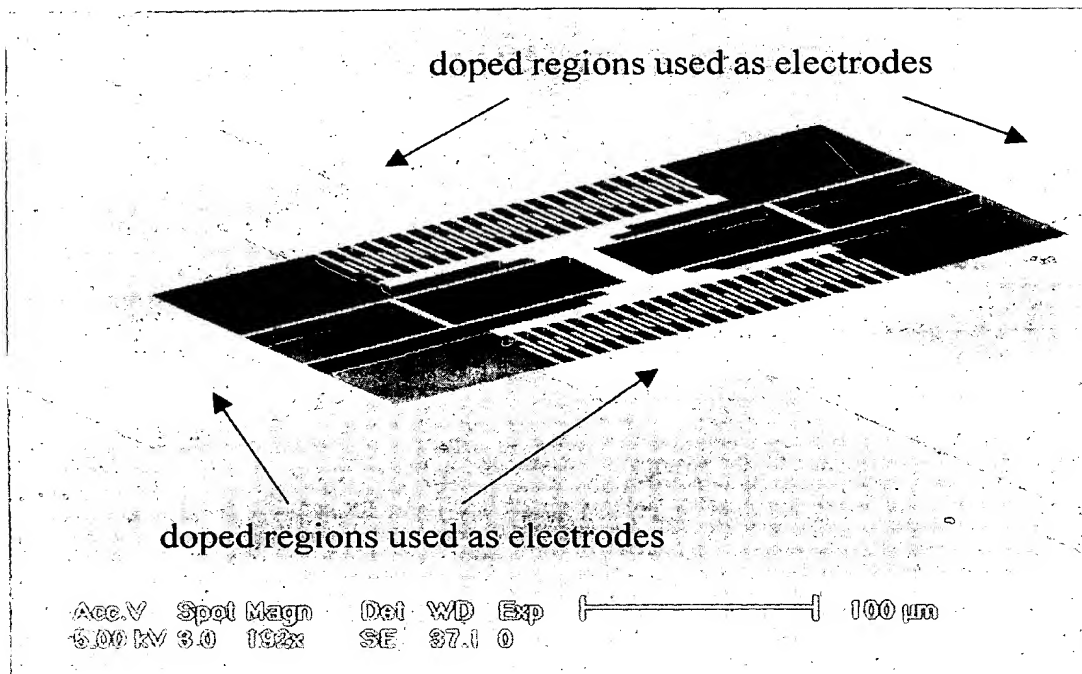




FIG. 4
(Prior Art)

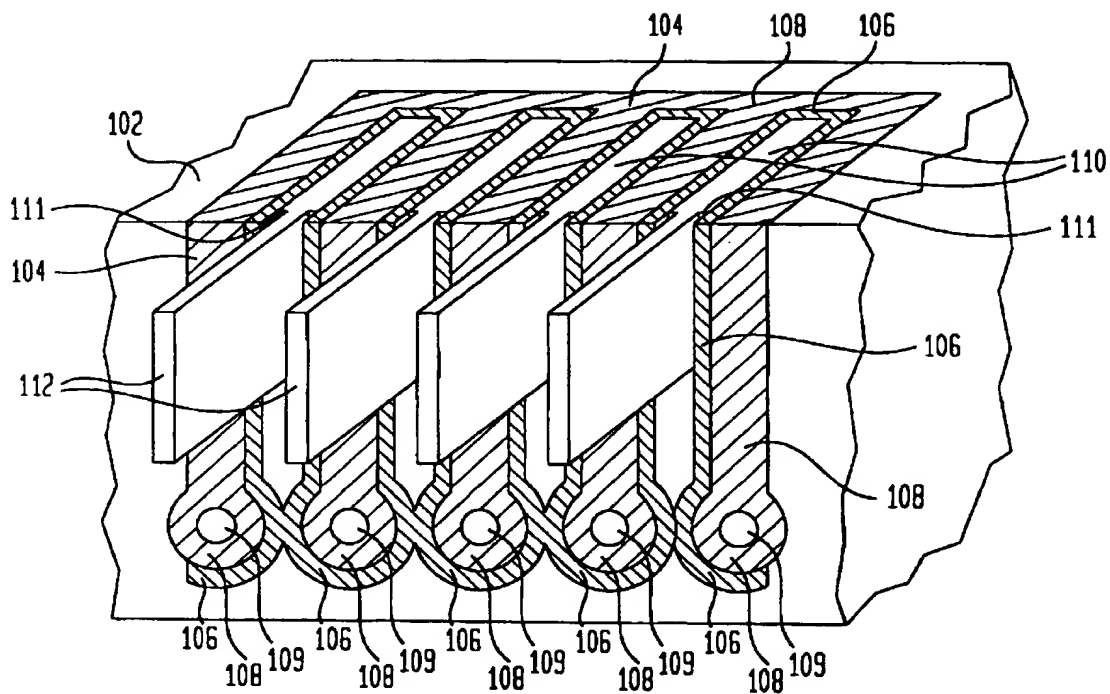




FIG. 5
(Prior Art)

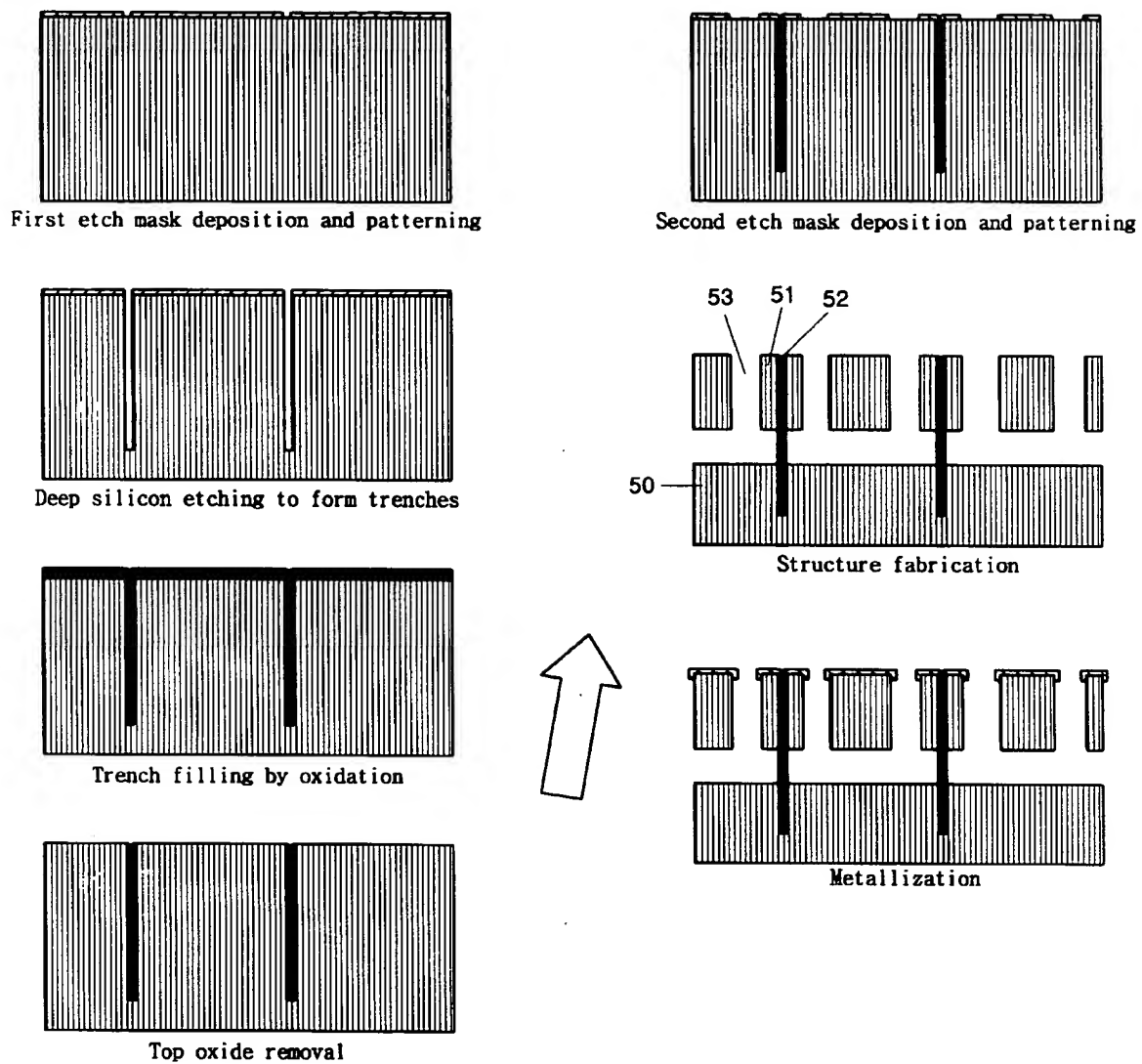
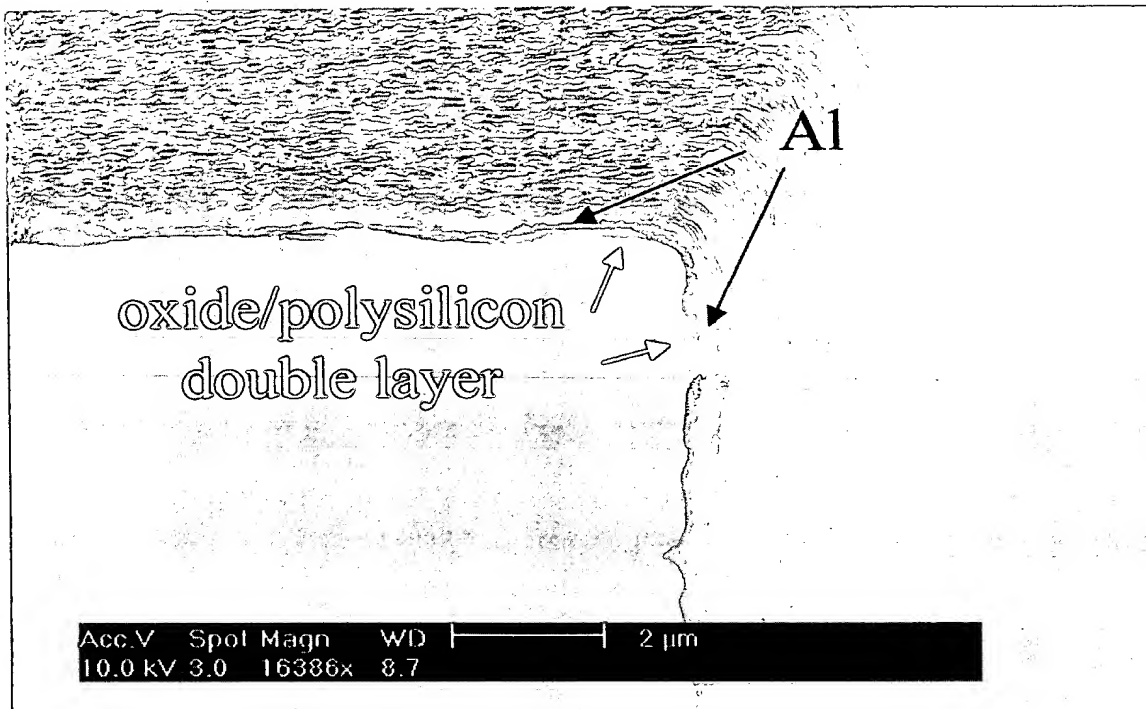




FIG. 7A



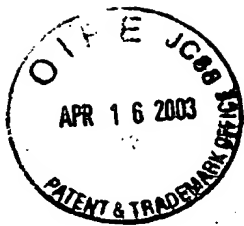


FIG. 7B

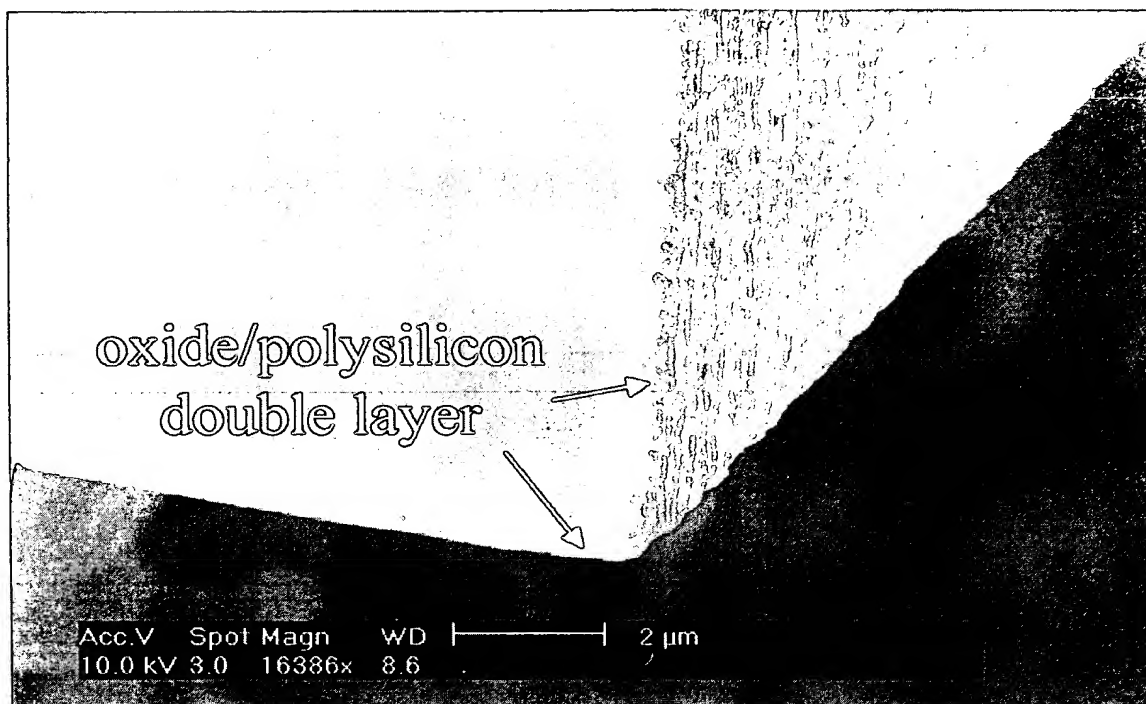




FIG. 9

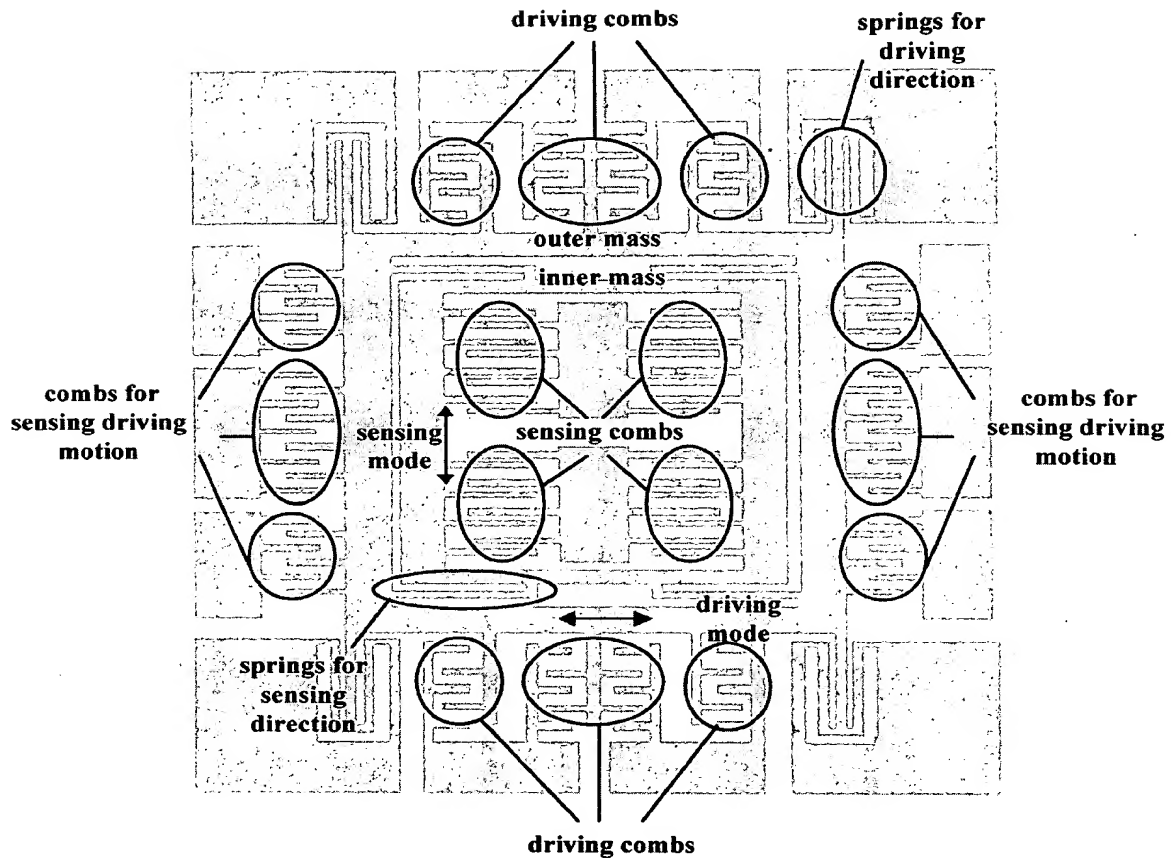
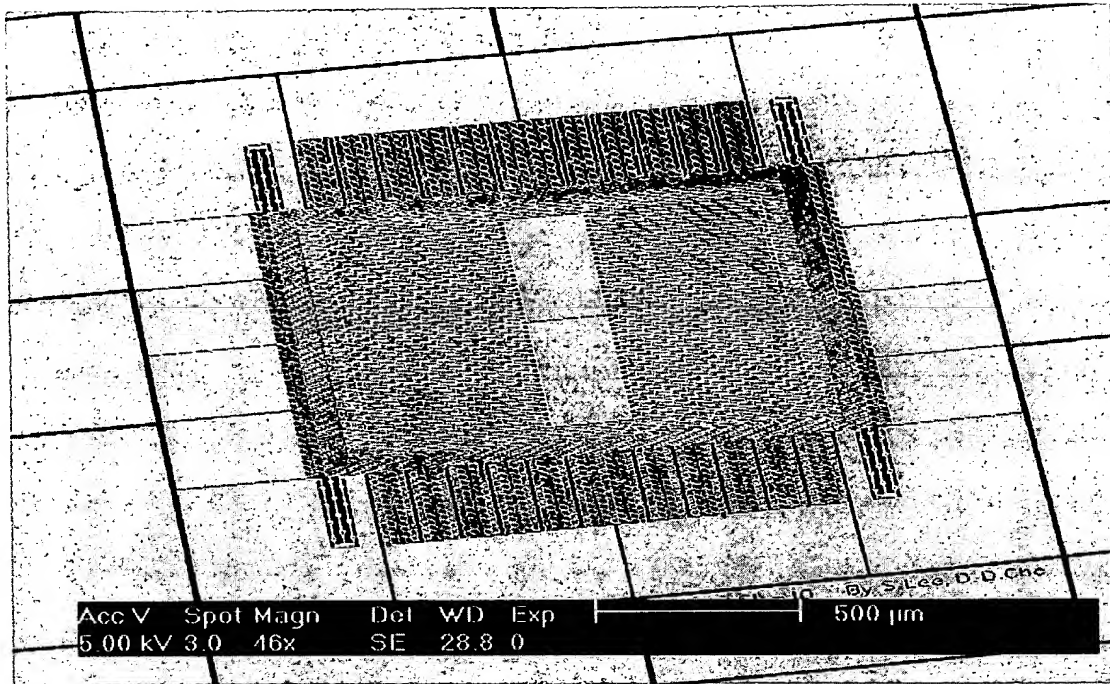




FIG. 12A



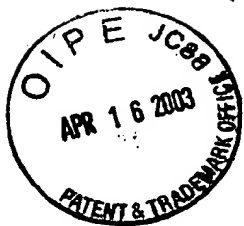
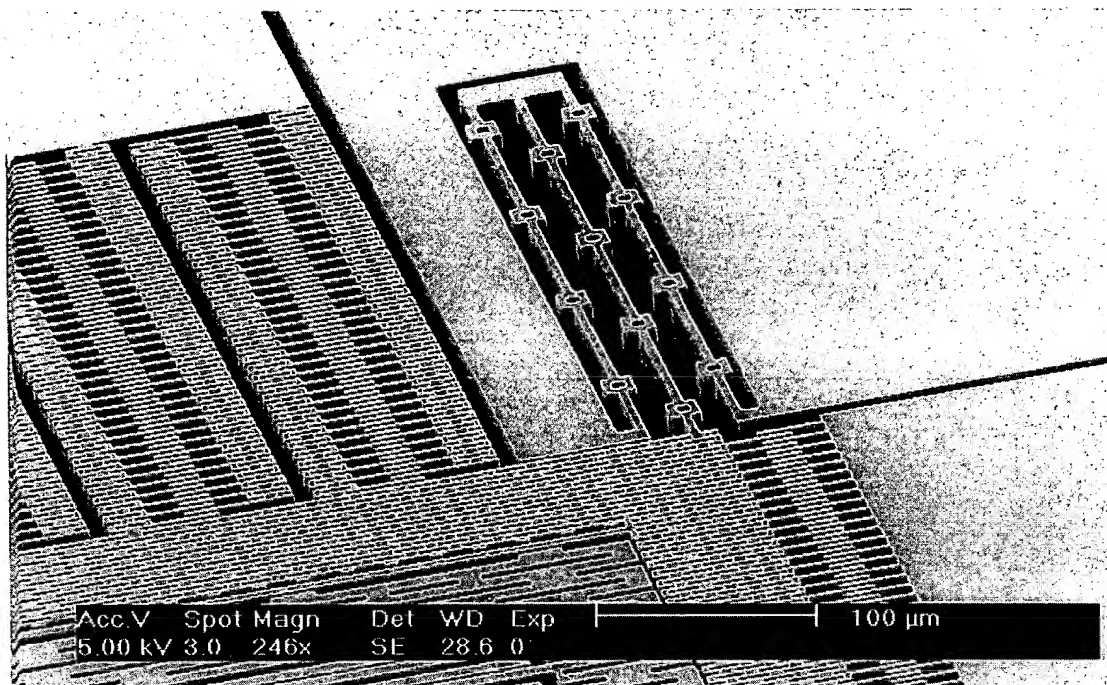


FIG. 12B



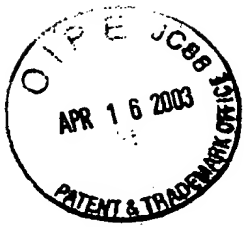


FIG. 12C

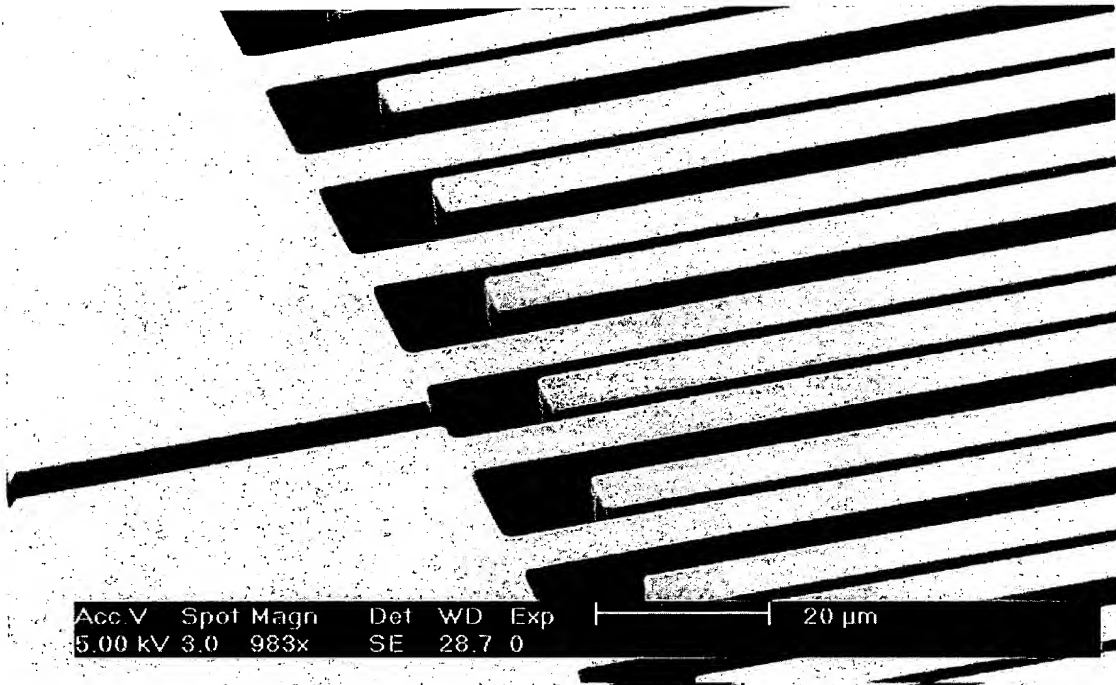
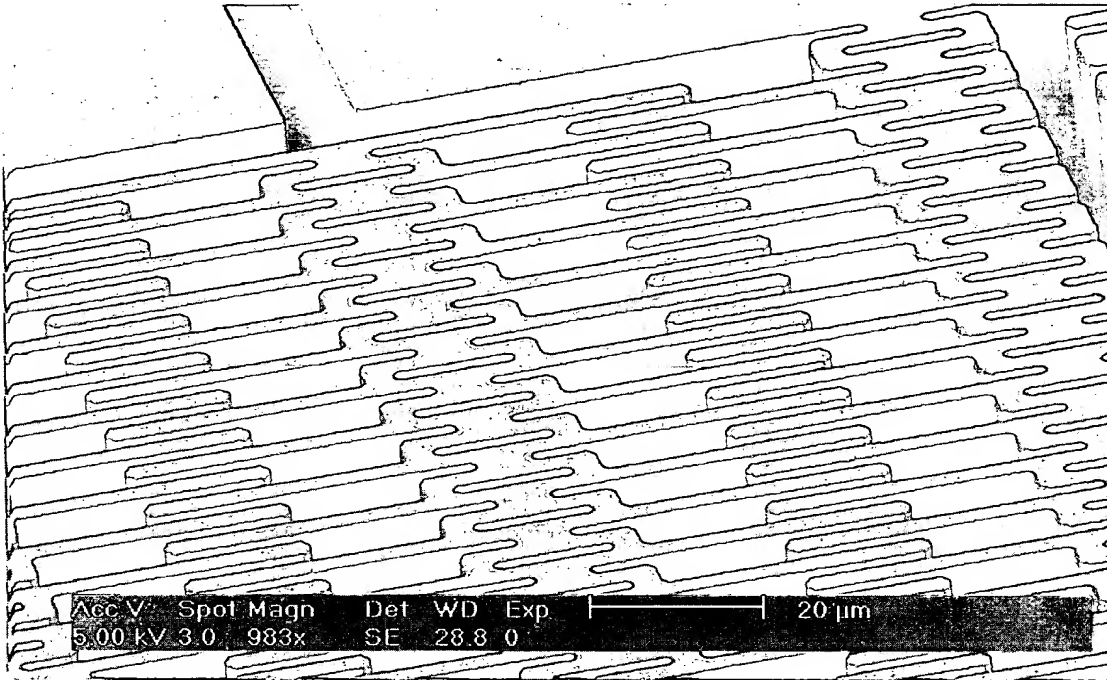




FIG. 12D



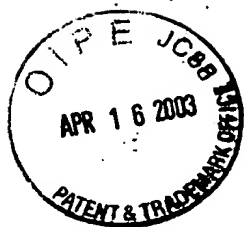


FIG. 12E

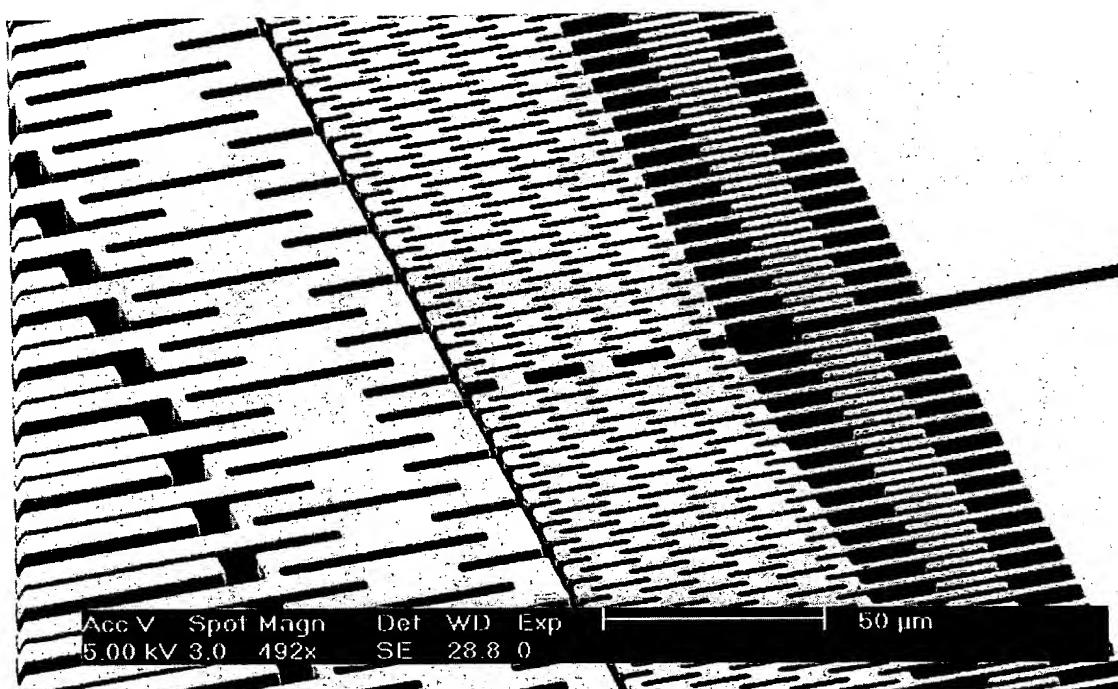




FIG. 13

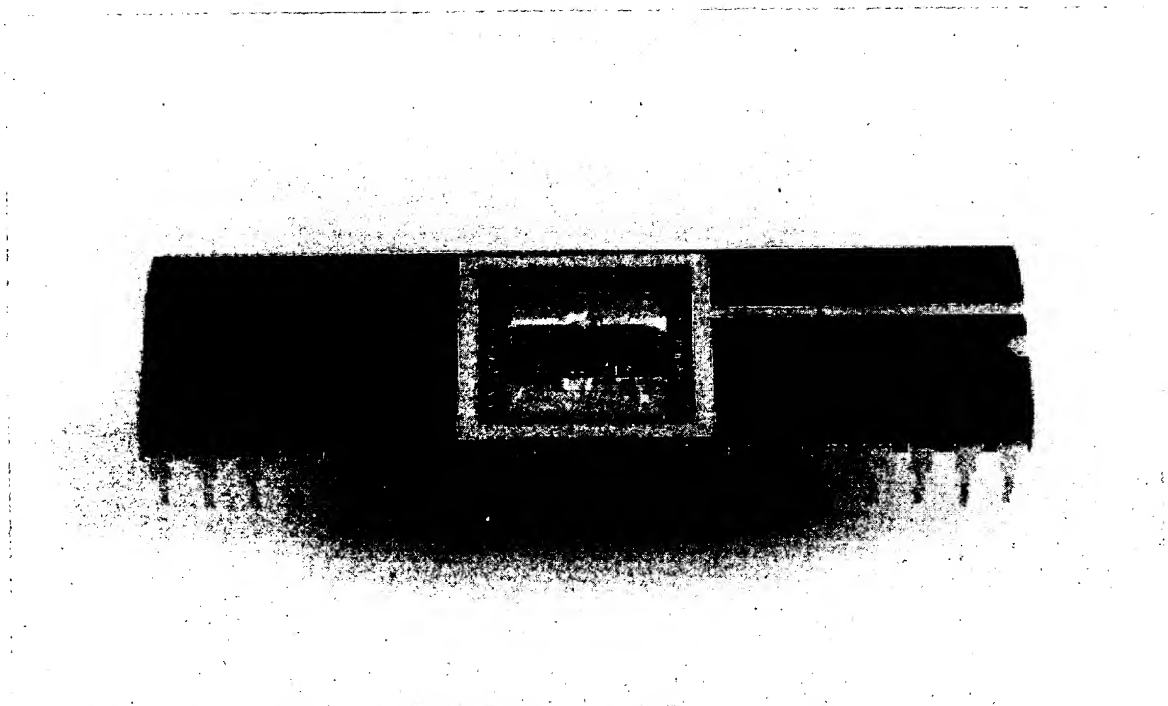
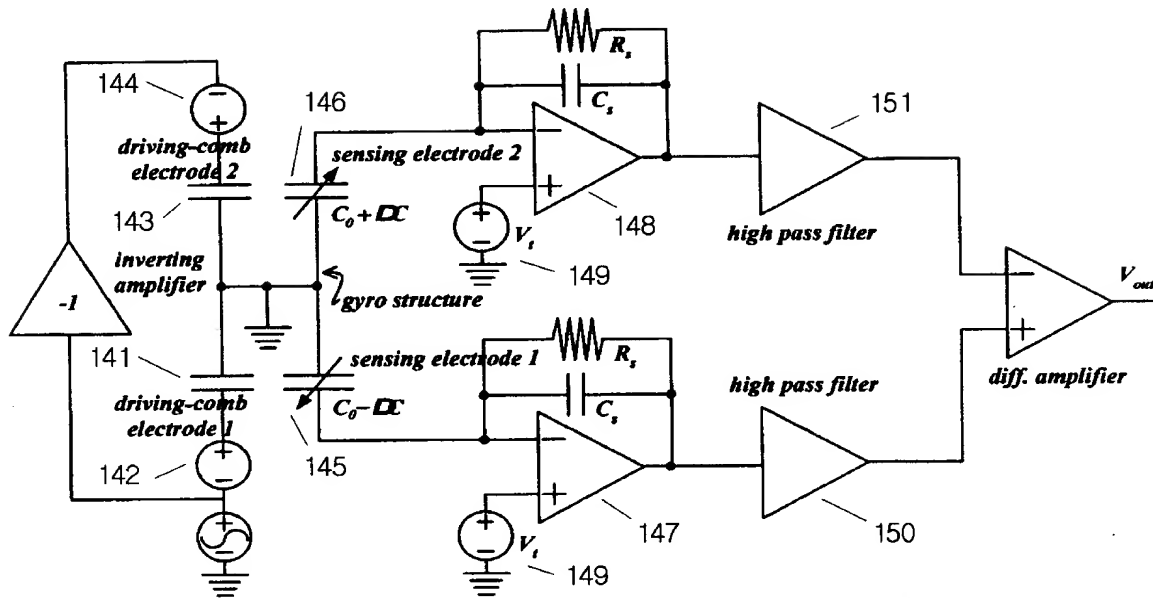




FIG. 14



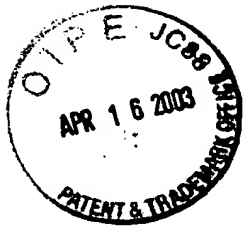
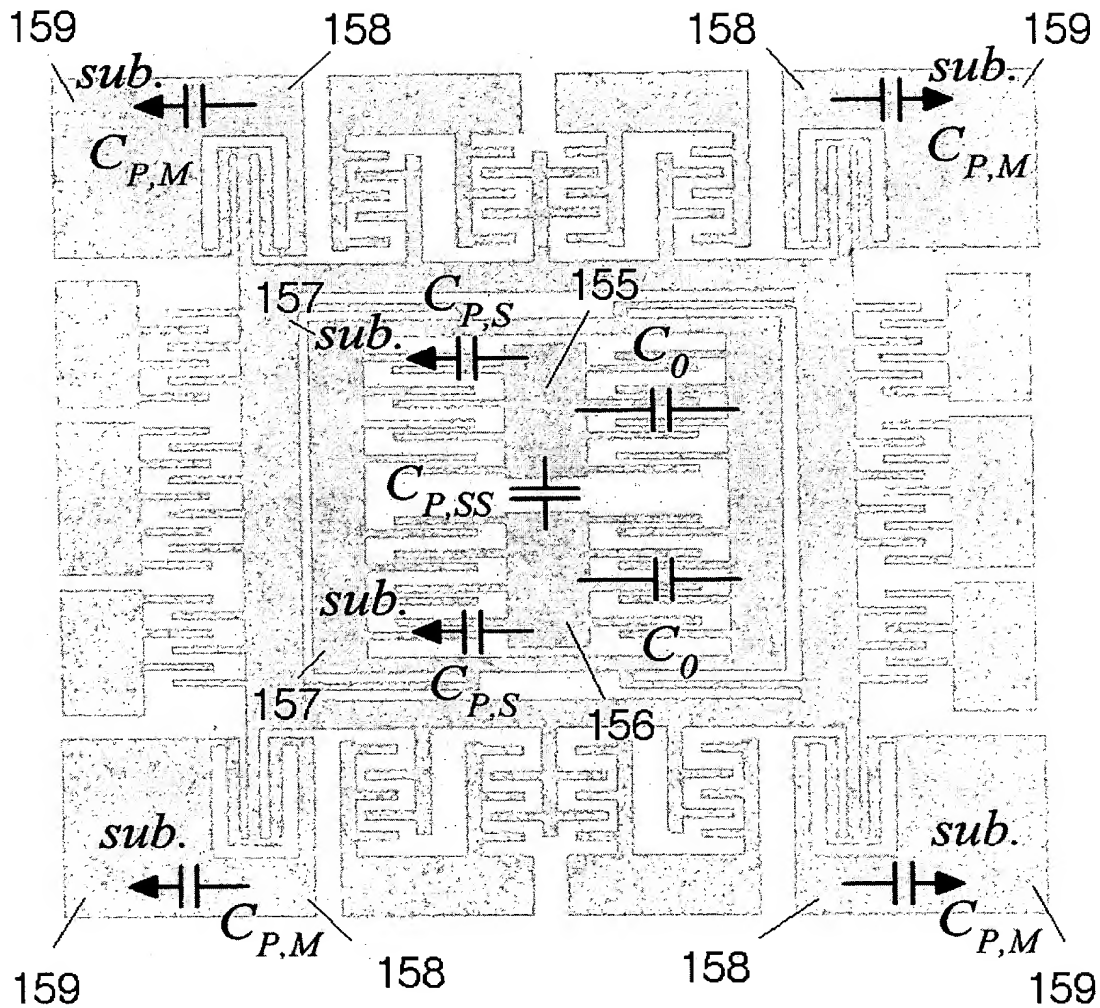
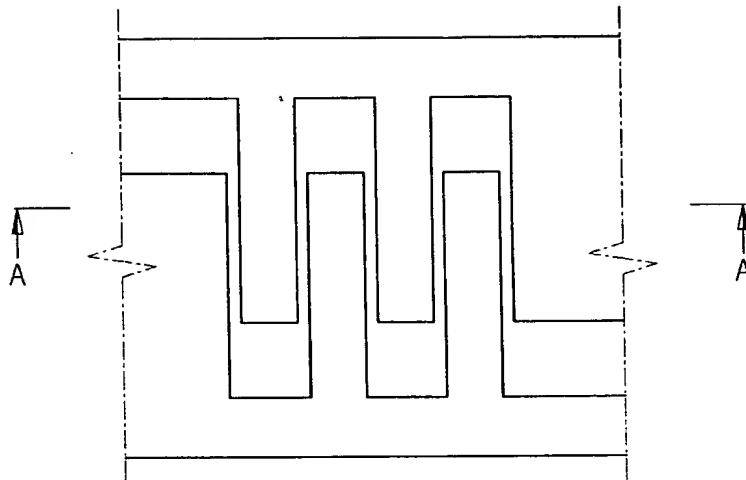


FIG. 15A





[Fig. 20]



[Fig. 21]

